

Attorney Docket No.: 0254-094-CIP4/CIP-MB

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Title: Stacked Module Systems and Methods
Application No.: TBA
Filing Date: 04/20/2004
Inventor: Julian Partridge & James D. Wehrly, Jr.
Assignee: Staktek Group, L.P.
Examiner: TBA
Group: TBA

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

Pursuant to the guidelines for Information Disclosure Statements, 37 C.F.R. §§ 1.97-1.98, attached hereto is PTO Form 1449 (five sheets) with references listed for consideration by the Office.

In accordance with 37 C.F.R. § 1.98(a), copies of the listed written references are being provided.

In accordance with 37 C.F.R. §§ 1.97(g)-(h), the filing of this Information Disclosure Statement shall not be construed as a representation that a search has been made or an admission that the information cited in the statement is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b) or prior art under 35 U.S.C. §§ 102 or 103.

This Information Disclosure Statement is being filed before receipt of the first Office action, so no fee is believed to be due. The Commissioner is hereby authorized to charge any fees which may be required in connection with the filing, or to credit any overpayment to Deposit Account No. 50-0897, upon which account the undersigned has the authority to sign. A **duplicate copy of Form 1449 is enclosed.**

Respectfully submitted,

ANDREWS & KURTH LLP

April 20, 2004
Date

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Form PTO-1449 (Modified)
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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use several sheets if necessary)

APPLICANT

Julian Partridge & James D. Wehrly, Jr.

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GROUP

4/20/2004

(37 CFR 1.98(b))

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						Yes	No
	58-96756(A)	06/08/1983	Japan			Partial	
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						Yes	No
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